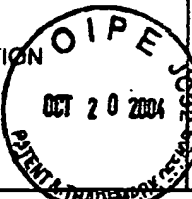


<b>Subst. Form PTO-1449</b>  <b>INFORMATION DISCLOSURE CITATION IN AN APPLICATION</b>  <i>(Use several sheets if necessary)</i>				Docket Number (Optional) <b>56247-235 (CSLL-662CP)</b>		Application Number <b>10/642,315</b>	
				Applicant <b>Sawyer, et al.</b>		Filing Date <b>8/15/2003</b>	
<b>U. S. Patent Documents</b>				Group Art Unit <b>2813</b>			

EXAMINER INITIAL	REF	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
DS		6,077,721	06-2000	Fukuda et al.			
		6,277,666	08-2001	Hays et al.			
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		4,079,508	03-1979	Nunn			
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		6,458,615	10-2002	Fedder, et al.			
↓		5,501,893	03-1996	Laermer, et al.			

FOREIGN PATENT DOCUMENTS							
REF	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						YES	NO

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)	
	Copy of International Search Report PCT/US02/00015
DS	C1 Moore DF, "Silicon-on insulator material for sensors and accelerometers" Silicon Fabricated Inertial instruments, 9/1-9/5 (December 1996)
↓	C2 Syms RRA et al., "Surface tension powered self-assembly of 3D MOEMS devices using DRIE of bonded silicon-on-insulator wafers." IEEE Seminar on Demonstrated Micromachining Technologies for Industry, 1/1-1/6 (March 2000)
↓	C3 Yamamoto T et al. "Capacitive accelerometer with high aspect ratio single crystalline silicon microstructure using SOI structure with polysilicon-based interconnect technique." Micro Electro Mechanical Systems, 515-519 (January 2000)
↓	C4 Martin A. Schmidt, "Wafer-to-Wafer Bonding for Microstructure Formation", Proceedings of the IEEE, Vol. 86, No. 8, August 1998.

EXAMINER <b>DS</b>	DATE CONSIDERED <b>1/23/05</b>
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EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy with next communication to applicant.